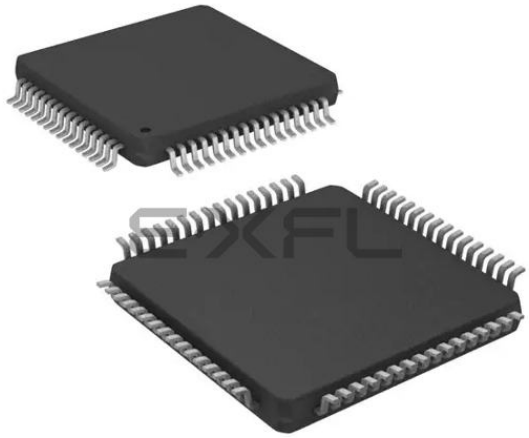

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Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	53
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 36x10/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ev128gm006-e-pt

Referenced Sources

This device data sheet is based on the following individual chapters of the *"dsPIC33/PIC24 Family Reference Manual"*, which are available from the Microchip web site (www.microchip.com). The following documents should be considered as the general reference for the operation of a particular module or device feature:

- **"Introduction"** (DS70573)
- **"CPU"** (DS70359)
- **"Data Memory"** (DS70595)
- **"dsPIC33E/PIC24E Program Memory"** (DS70000613)
- **"Flash Programming"** (DS70609)
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- **"Input Capture"** (DS70000352)
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- **"High-Speed PWM"**(DS70645)
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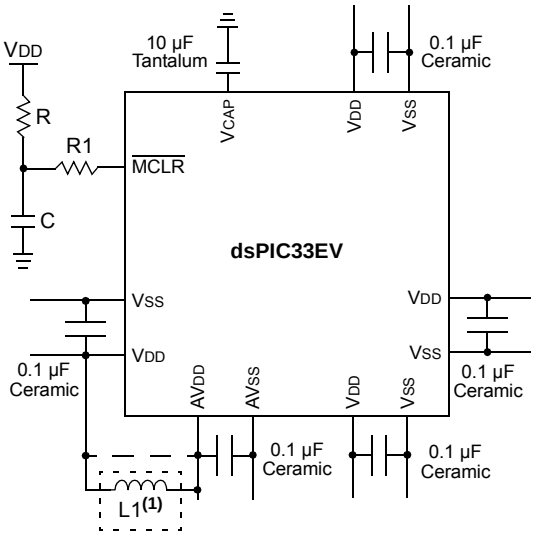
- **"Serial Peripheral Interface (SPI)"** (DS70005185)
- **"Inter-Integrated Circuit™ (I^2C™)"** (DS70000195)
- **"Enhanced Controller Area Network (ECAN™)"**(DS70353)
- **"Direct Memory Access (DMA)"** (DS70348)
- **"Programming and Diagnostics"** (DS70608)
- **"Op Amp/Comparator"** (DS70000357)
- **"Device Configuration"** (DS70000618)
- **"Charge Time Measurement Unit (CTMU)"** (DS70661)
- **"Single-Edge Nibble Transmission (SENT) Module"** (DS70005145)

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 1Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{FCNV}{2} \quad \text{(i.e., ADC Conversion Rate/2)}$$

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

2.3 CPU Logic Filter Capacitor Connection (VCAP)

A low-ESR (<1 Ohms) capacitor is required on the VCAP pin, which is used to stabilize the internal voltage regulator output. The VCAP pin must not be connected to VDD, and must have a capacitor greater than 4.7 µF (10 µF is recommended), with at least a 16V rating connected to the ground. The type can be ceramic or tantalum. See **Section 30.0 "Electrical Characteristics"** for additional information.

The placement of this capacitor should be close to the VCAP pin. It is recommended that the trace length should not exceed one-quarter inch (6 mm).

2.4 Master Clear (MCLR) Pin

The MCLR pin provides two specific device functions:

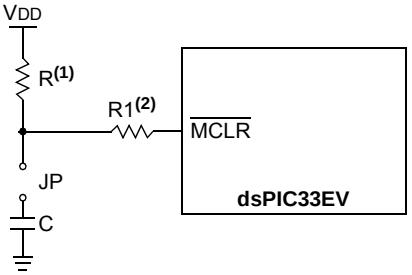
- Device Reset
- Device Programming and Debugging

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-1, it is recommended that the capacitor, C, be isolated from the MCLR pin during programming and debugging operations.

Place the components as shown in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the MCLR pin VIH and VIL specifications are met.

2: R1 ≤ 470Ω will limit any current flow into MCLR from the external capacitor, C, in the event of MCLR pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met.

TABLE 4-2: TIMERS REGISTER MAP

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
TMR1	0100	Timer1 Register																0000
PR1	0102	Period Register 1																FFFF
T1CON	0104	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	TSYNC	TCS	—	0000
TMR2	0106	Timer2 Register																0000
TMR3HLD	0108	Timer3 Holding Register (For 32-bit timer operations only)																0000
TMR3	010A	Timer3 Register																0000
PR2	010C	Period Register 2																FFFF
PR3	010E	Period Register 3																FFFF
T2CON	0110	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—	0000
T3CON	0112	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	—	TCS	—	0000
TMR4	0114	Timer4 Register																0000
TMR5HLD	0116	Timer5 Holding Register (For 32-bit operations only)																0000
TMR5	0118	Timer5 Register																0000
PR4	011A	Period Register 4																FFFF
PR5	011C	Period Register 5																FFFF
T4CON	011E	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	T32	—	TCS	—	0000
T5CON	0120	TON	—	TSIDL	—	—	—	—	—	—	TGATE	TCKPS1	TCKPS0	—	—	TCS	—	0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 4-16: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP FOR dsPIC33EVXXXGM006/106 DEVICES

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
RPOR0	0670	—	—	RP35R5	RP35R4	RP35R3	RP35R2	RP35R1	RP35R0	—	—	RP20R5	RP20R4	RP20R3	RP20R2	RP20R1	RP20R0	0000
RPOR1	0672	—	—	RP37R5	RP37R4	RP37R3	RP37R2	RP37R1	RP37R0	—	—	RP36R5	RP36R4	RP36R3	RP36R2	RP36R1	RP36R0	0000
RPOR2	0674	—	—	RP39R5	RP39R4	RP39R3	RP39R2	RP39R1	RP39R0	—	—	RP38R5	RP38R4	RP38R3	RP38R2	RP38R1	RP38R0	0000
RPOR3	0676	—	—	RP41R5	RP41R4	RP41R3	RP41R2	RP41R1	RP41R0	—	—	RP40R5	RP40R4	RP40R3	RP40R2	RP40R1	RP40R0	0000
RPOR4	0678	—	—	RP43R5	RP43R4	RP43R3	RP43R2	RP43R1	RP43R0	—	—	RP42R5	RP42R4	RP42R3	RP42R2	RP42R1	RP42R0	0000
RPOR5	067A	—	—	RP49R5	RP49R4	RP49R3	RP49R2	RP49R1	RP49R0	—	—	RP48R5	RP48R4	RP48R3	RP48R2	RP48R1	RP48R0	0000
RPOR6	067C	—	—	RP55R5	RP55R4	RP55R3	RP55R2	RP55R1	RP55R0	—	—	RP54R5	RP54R4	RP54R3	RP54R2	RP54R1	RP54R0	0000
RPOR7	067E	—	—	RP57R5	RP57R4	RP57R3	RP57R2	RP57R1	RP57R0	—	—	RP56R5	RP56R4	RP56R3	RP56R2	RP56R1	RP56R0	0000
RPOR8	0680	—	—	RP70R5	RP70R4	RP70R3	RP70R2	RP70R1	RP70R0	—	—	RP69R5	RP69R4	RP69R3	RP69R2	RP69R1	RP69R0	0000
RPOR9	0682	—	—	RP118R5	RP118R4	RP118R3	RP118R2	RP118R1	RP118R0	—	—	RP97R5	RP97R4	RP97R3	RP97R2	RP97R1	RP97R0	0000
RPOR10	0684	—	—	RP176R5	RP176R4	RP176R3	RP176R2	RP176R1	RP176R0	—	—	RP120R5	RP120R4	RP120R3	RP120R2	RP120R1	RP120R0	0000
RPOR11	0686	—	—	RP178R5	RP178R4	RP178R3	RP178R2	RP178R1	RP178R0	—	—	RP177R5	RP177R4	RP177R3	RP177R2	RP177R1	RP177R0	0000
RPOR12	0688	—	—	RP180R5	RP180R4	RP180R3	RP180R2	RP180R1	RP180R0	—	—	RP179R5	RP179R4	RP179R3	RP179R2	RP179R1	RP179R0	0000
RPOR13	068A	—	—	—	—	—	—	—	—	—	—	RP181R<5:0>						0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

REGISTER 5-4: NVMKEY: NONVOLATILE MEMORY KEY REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

W-0	W-0	W-0	W-0	W-0	W-0	W-0	W-0
NVMKEY<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7-0 **NVMKEY<7:0>:** NVM Key Register bits (write-only)

REGISTER 7-4: INTCON2: INTERRUPT CONTROL REGISTER 2

R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0	R/W-0
GIE	DISI	SWTRAP	—	—	—	—	AIVTEN
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	INT2EP	INT1EP	INT0EP
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **GIE:** Global Interrupt Enable bit
1 = Interrupts and associated IECx bits are enabled
0 = Interrupts are disabled, but traps are still enabled

bit 14 **DISI:** DISI Instruction Status bit
1 = DISI instruction is active
0 = DISI instruction is not active

bit 13 **SWTRAP:** Software Trap Status bit
1 = Software trap is enabled
0 = Software trap is disabled

bit 12-9 **Unimplemented:** Read as ‘0’

bit 8 **AIVTEN:** Alternate Interrupt Vector Table is Enabled bit
1 = AIVT is enabled
0 = AIVT is disabled

bit 7-3 **Unimplemented:** Read as ‘0’

bit 2 **INT2EP:** External Interrupt 2 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 1 **INT1EP:** External Interrupt 1 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

bit 0 **INT0EP:** External Interrupt 0 Edge Detect Polarity Select bit
1 = Interrupt on negative edge
0 = Interrupt on positive edge

13.0 TIMER2/3 AND TIMER4/5

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Timers"** (DS70362) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

These modules are 32-bit timers, which can also be configured as four independent, 16-bit timers with selectable operating modes.

As a 32-bit timer, Timer2/3 and Timer4/5 operate in the following three modes:

- Two Independent 16-Bit Timers (e.g., Timer2 and Timer3) with all 16-Bit Operating modes (except Asynchronous Counter mode)
- Single 32-Bit Timer
- Single 32-Bit Synchronous Counter

They also support these features:

- Timer Gate Operation
- Selectable Prescaler Settings
- Timer Operation during Idle and Sleep modes
- Interrupt on a 32-Bit Period Register Match
- Time Base for Input Capture and Output Compare Modules
- ADC1 Event Trigger (Timer2/3 only)

Individually, all four of the 16-bit timers can function as synchronous timers or counters. They also offer the features listed previously, except for the event trigger; this is implemented only with Timer2/3. The operating modes and enabled features are determined by setting the appropriate bit(s) in the T2CON, T3CON, T4CON and T5CON registers. T2CON and T4CON are shown in generic form in Register 13-1. The T3CON and T5CON registers are shown in Register 13-2.

For 32-bit timer/counter operation, Timer2 and Timer4 are the least significant word (lsw). Timer3 and Timer5 are the most significant word (msw) of the 32-bit timers.

Note: For 32-bit operation, the T3CON and T5CON control bits are ignored. Only the T2CON and T4CON control bits are used for setup and control. Timer2 and Timer4 clock and gate inputs are utilized for the 32-bit timer modules, but an interrupt is generated with the Timer3 and Timer5 interrupt flags.

Block diagrams for the Type B and Type C timers are shown in Figure 13-1 and Figure 13-2, respectively.

A block diagram for an example 32-bit timer pair (Timer2/3 and Timer4/5) is shown in Figure 13-3.

Note: Only Timer2, Timer3, Timer4 and Timer5 can trigger a DMA data transfer.

16.0 OUTPUT COMPARE

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Output Compare"** (DS70005157) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

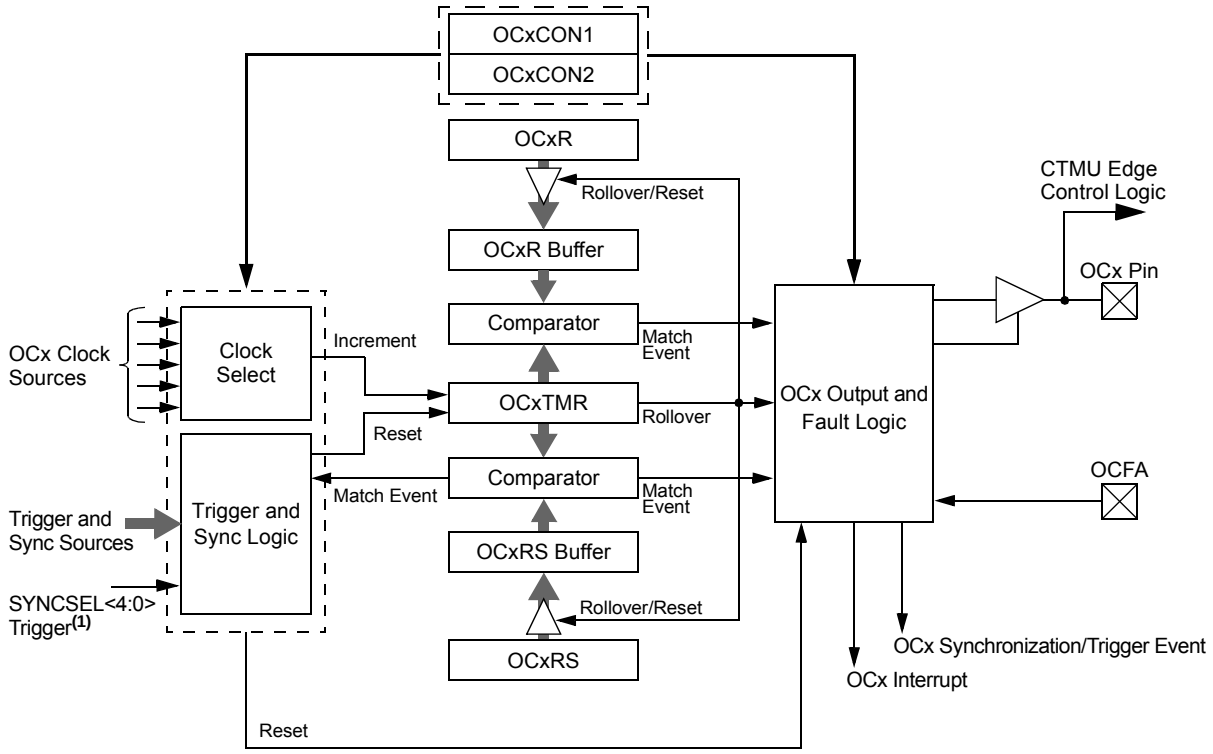
2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EVXXXGM00X/10X family devices support up to 4 output compare modules. The output compare module can select one of eight available clock sources for its time base. The module compares the value of the timer with the value of one or two Compare registers, depending on the operating mode selected. The state of the output pin changes when the timer value matches the Compare register value. The output compare module generates either a single output pulse, or a sequence of output pulses, by changing the state of the output pin on the compare match events. The output compare module can also generate interrupts on compare match events and trigger DMA data transfers.

Figure 16-1 shows a block diagram of the output compare module.

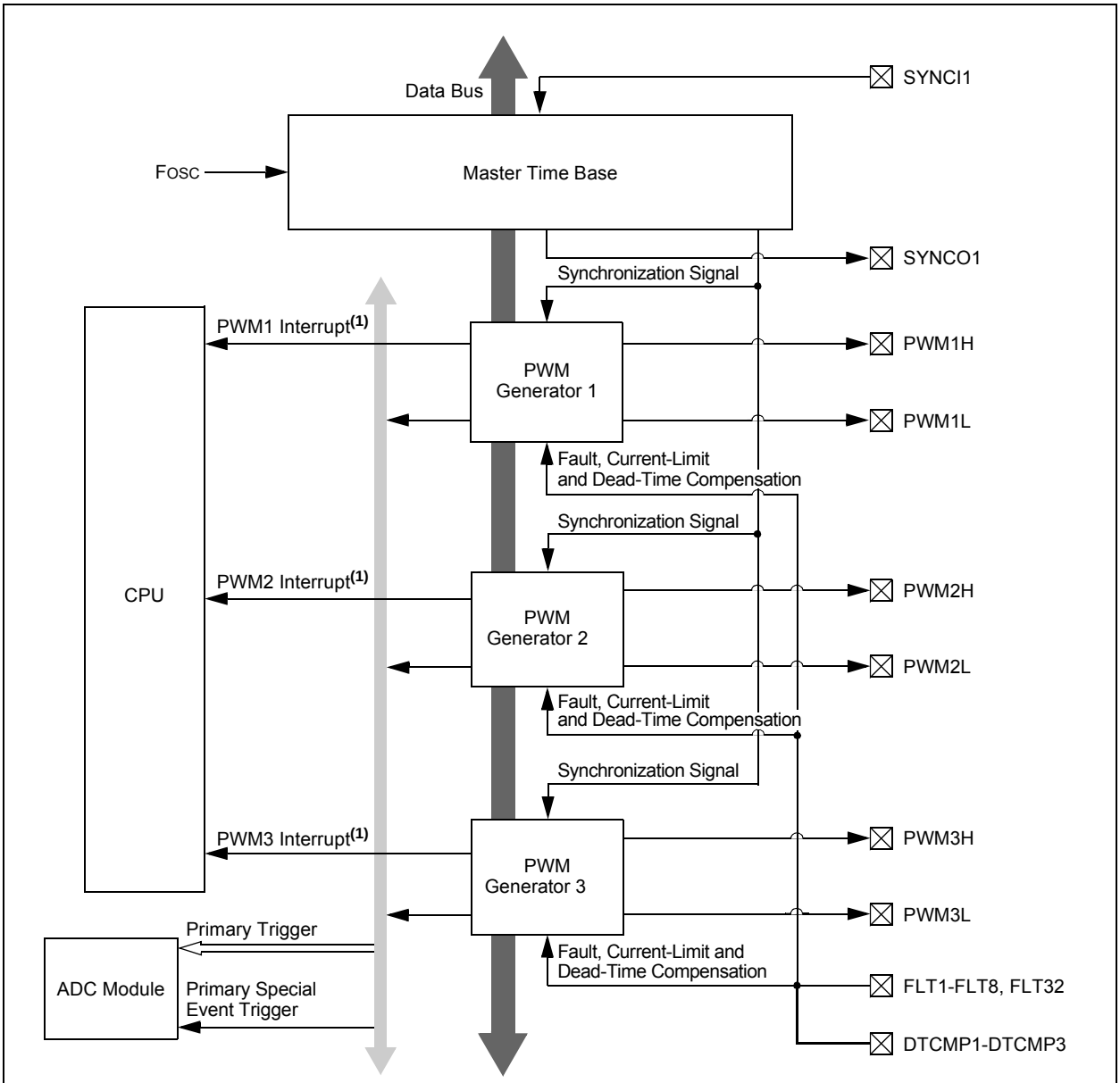
Note: For more information on OCxR and OCxRS register restrictions, refer to the **"Output Compare"** (DS70005157) section in the *"dsPIC33/PIC24 Family Reference Manual"*.

FIGURE 16-1: OUTPUT COMPARE x MODULE BLOCK DIAGRAM



Note 1: The trigger/sync source is enabled by default and is set to Timer2 as a source. This timer must be enabled for proper OCx module operation or the trigger/sync source must be changed to another source option.

FIGURE 17-1: HIGH-SPEED PWMx MODULE ARCHITECTURAL OVERVIEW



Note 1: The PWM interrupts are generated by logically ORing the FLTSTAT, CLSTAT and TRGSTAT status bits for the given PWM generator. For more information, refer to **"High-Speed PWM"** (DS70645) in the *"dsPIC33/PIC24 Family Reference Manual"*.

23.0 CHARGE TIME MEASUREMENT UNIT (CTMU)

Note 1: This data sheet summarizes the features of the dsPIC33EVXXXGM00X/10X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Charge Time Measurement Unit (CTMU)"** (DS70661) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available on the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Charge Time Measurement Unit (CTMU) is a flexible analog module that provides accurate differential time measurement between pulse sources, as well as asynchronous pulse generation. Its key features include:

- Nine Edge Input Trigger Sources
- Polarity Control for Each Edge Source
- Control of Edge Sequence
- Control of Response to Edges
- Time Measurement Resolution Down to 200 ps
- Accurate Current Source Suitable for Capacitive Measurement
- On-Chip Temperature Measurement using a Built-in Diode
- Pulse Generation Generates a Pulse using the C1INB Comparator Input and Outputs the Pulse onto the CTPLS Remappable Output

Together with other on-chip analog modules, the CTMU can be used to precisely measure time, measure capacitance, measure relative changes in capacitance or generate output pulses that are independent of the system clock.

The CTMU module is ideal for interfacing with capacitive-based sensors. The CTMU is controlled through three registers: CTMUCON1, CTMUCON2 and CTMUICON. CTMUCON1 and CTMUCON2 enable the module and control edge source selection, edge source polarity selection and edge sequencing. The CTMUICON register controls the selection and trim of the current source.

23.1 CTMU Control Registers

REGISTER 23-1: CTMUCON1: CTMU CONTROL REGISTER 1

R/W-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CTMUEN	—	CTMUSIDL	TGEN(2)	EDGEN	EDGSEQEN	IDISSEN(1)	CTTRIG
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CTMUEN:** CTMU Enable bit
1 = Module is enabled
0 = Module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **CTMUSIDL:** CTMU Stop in Idle Mode bit
1 = Discontinues module operation when the device enters Idle mode
0 = Continues module operation in Idle mode

bit 12 **TGEN:** Time Generation Enable bit(2)
1 = Edge delay generation is enabled
0 = Edge delay generation is disabled

bit 11 **EDGEN:** Edge Enable bit
1 = Hardware modules are used to trigger edges (TMRx, CTEDx, etc.)
0 = Software is used to trigger edges (manual set of EDGxSTAT)

bit 10 **EDGSEQEN:** Edge Sequence Enable bit
1 = Edge 1 event must occur before Edge 2 event can occur
0 = No edge sequence is needed

bit 9 **IDISSEN:** Analog Current Source Control bit(1)
1 = Analog current source output is grounded
0 = Analog current source output is not grounded

bit 8 **CTTRIG:** ADC Trigger Control bit
1 = CTMU triggers the ADC start of conversion
0 = CTMU does not trigger the ADC start of conversion

bit 7-0 **Unimplemented:** Read as '0'

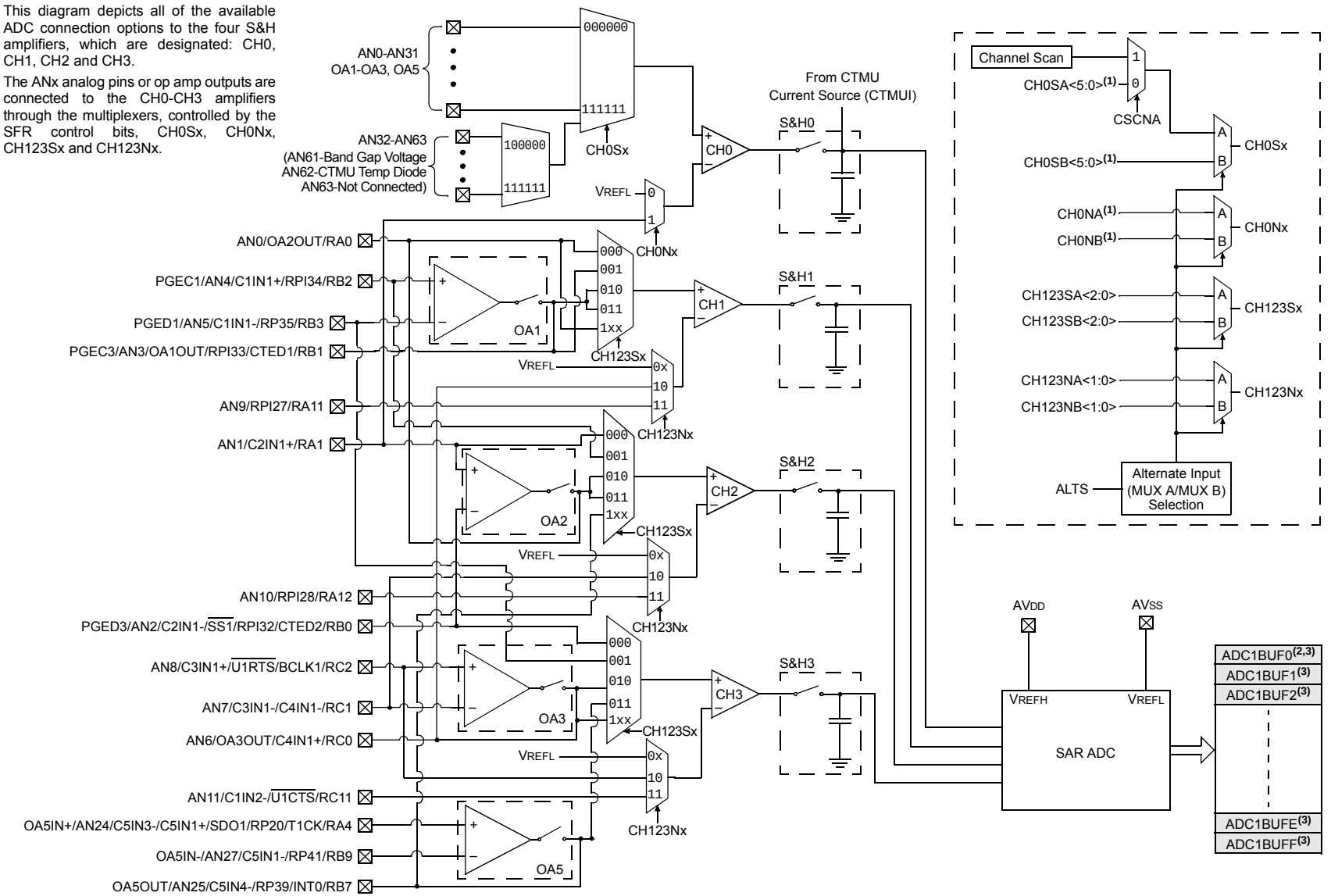
Note 1: The ADC module Sample-and-Hold (S&H) capacitor is not automatically discharged between sample/conversion cycles. Any software using the ADC as part of a capacitance measurement must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

2: If the TGEN bit is set to '1', then the CMP1 module should be selected as the Edge 2 source in the EDG2SELx bits field; otherwise, the module will not function.

FIGURE 24-1: ADCx MODULE BLOCK DIAGRAM WITH CONNECTION OPTIONS FOR ANx PINS AND OP AMPS

This diagram depicts all of the available ADC connection options to the four S&H amplifiers, which are designated: CH0, CH1, CH2 and CH3.

The ANx analog pins or op amp outputs are connected to the CH0-CH3 amplifiers through the multiplexers, controlled by the SFR control bits, CH0Sx, CH0Nx, CH123Sx and CH123Nx.



Note 1: Channels 1, 2 and 3 are not applicable for the 12-bit mode of operation.
2: When ADDMAEN (ADxCON4<8>) = 0, ADC1BUF0-ADC1BUFF are used.
3: When ADDMAEN (ADxCON4<8>) = 1 enabling DMA, only ADC1BUF0 is used.

REGISTER 25-3: CM4CON: COMPARATOR 4 CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	R/W-0	R-0
CON	COE	CPOL	—	—	—	CEVT	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1(2)	EVPOL0(2)	—	CREF(1)	—	—	CCH1(1)	CCH0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **CON:** Op Amp/Comparator 4 Enable bit
1 = Comparator is enabled
0 = Comparator is disabled

bit 14 **COE:** Comparator 4 Output Enable bit
1 = Comparator output is present on the C4OUT pin
0 = Comparator output is internal only

bit 13 **CPOL:** Comparator 4 Output Polarity Select bit
1 = Comparator output is inverted
0 = Comparator output is not inverted

bit 12-10 **Unimplemented:** Read as '0'

bit 9 **CEVT:** Comparator 4 Event bit
1 = Comparator event, according to EVPOL<1:0> settings, occurred; disables future triggers and interrupts until the bit is cleared
0 = Comparator event did not occur

bit 8 **COUT:** Comparator 4 Output bit
When CPOL = 0 (non-inverted polarity):
1 = VIN+ > VIN-
0 = VIN+ < VIN-
When CPOL = 1 (inverted polarity):
1 = VIN+ < VIN-
0 = VIN+ > VIN-

Note 1: Inputs that are selected and not available will be tied to VSS. See the **"Pin Diagrams"** section for available inputs for each package.

2: After configuring the comparator, either for a high-to-low or low-to-high COUT transition (EVPOL<1:0> (CMxCON<7:6>) = 10 or 01), the comparator Event bit, CEVT (CMxCON<9>), and the Comparator Combined Interrupt Flag, CMPIF (IFS1<2>), must be cleared before enabling the Comparator Interrupt Enable bit, CMPIE (IEC1<2>).

30.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33EVXXXGM00X/10X family electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the dsPIC33EVXXXGM00X/10X family are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

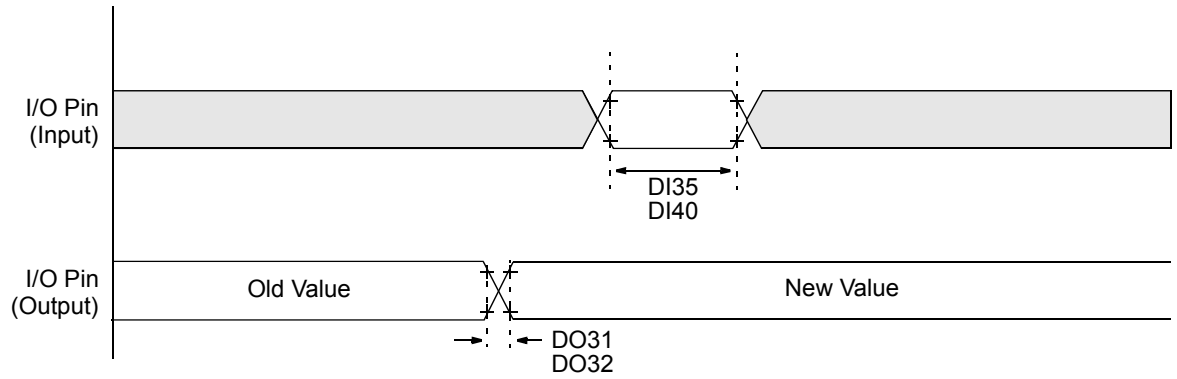
Absolute Maximum Ratings(1)

Ambient temperature under bias ..... -40°C to +125°C
Storage temperature ..... -65°C to +160°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +6.0V
Voltage on V_{CAP} with respect to V_{SS} ..... 1.62V to 1.98V
Maximum current out of V_{SS} pin ..... 350 mA
Maximum current into V_{DD} pin(2) ..... 350 mA
Maximum current sunk by any I/O pin ..... 20 mA
Maximum current sourced by I/O pin ..... 18 mA
Maximum current sourced/sunk by all ports(2) ..... 200 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 30-2).

FIGURE 30-3: I/O TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-21: I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 4.5V to 5.5V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
DO31	TIOR	Port Output Rise Time	—	5	10	ns	
DO32	TIOF	Port Output Fall Time	—	5	10	ns	
DI35	TINP	INTx Pin High or Low Time (input)	20	—	—	ns	
DI40	TRBP	CNx High or Low Time (input)	2	—	—	TCY	

Note 1: Data in "Typ." column is at 5.0V, +25°C unless otherwise stated.

FIGURE 30-4: BOR AND MASTER CLEAR RESET TIMING CHARACTERISTICS

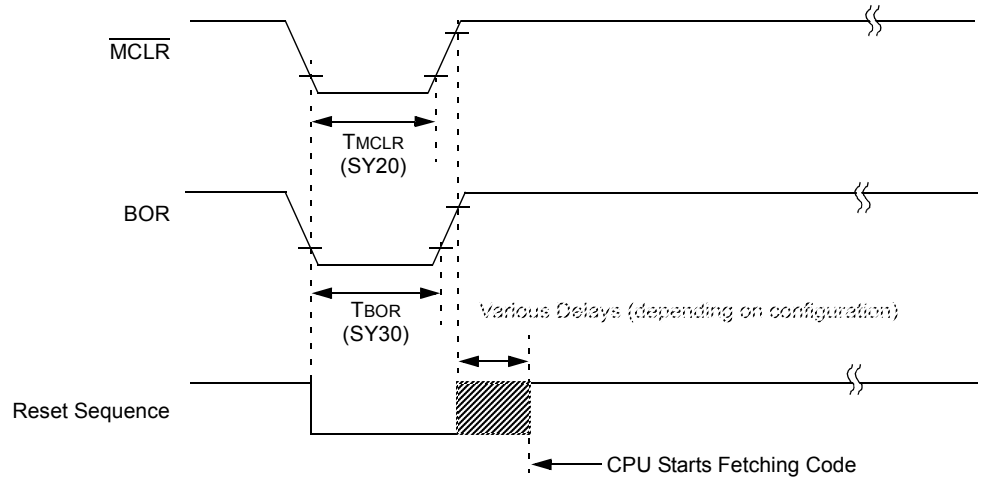


FIGURE 33-27: TYPICAL V_{OH} 4x DRIVER PINS vs. I_{OH} (GENERAL PURPOSE I/Os, TEMPERATURES AS NOTED)

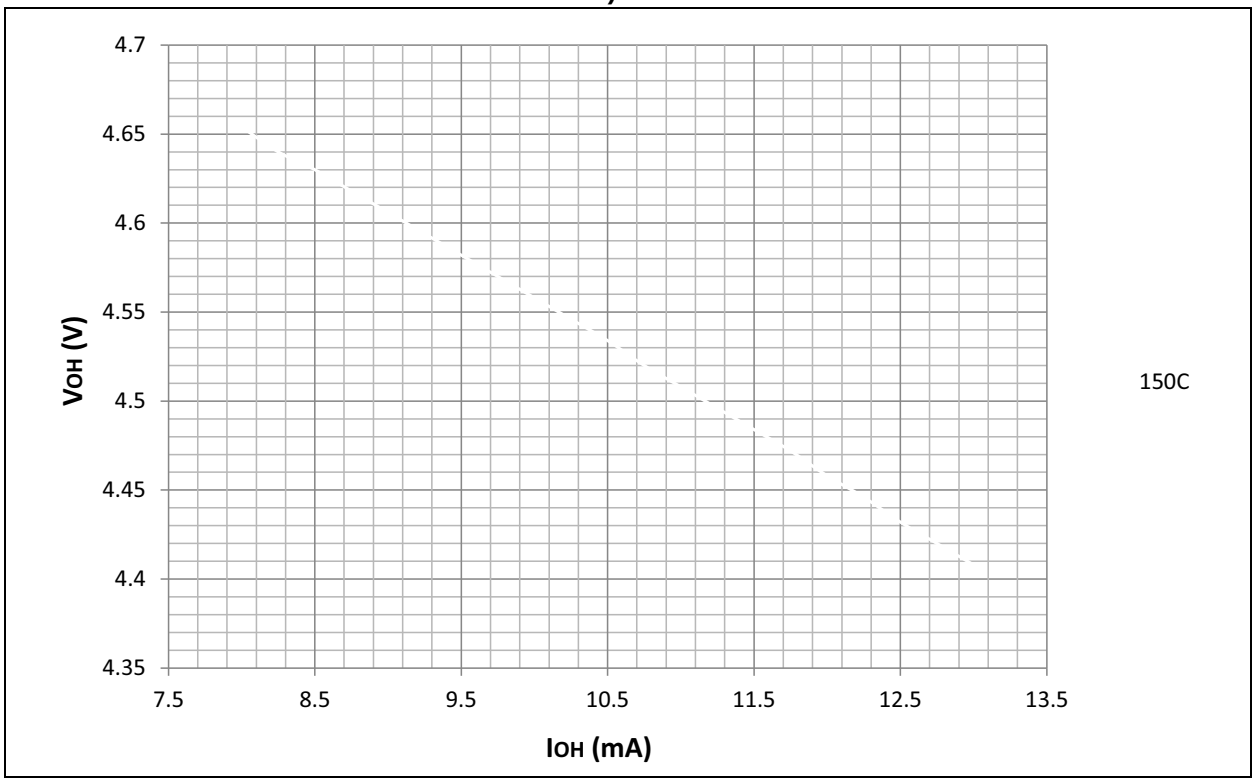
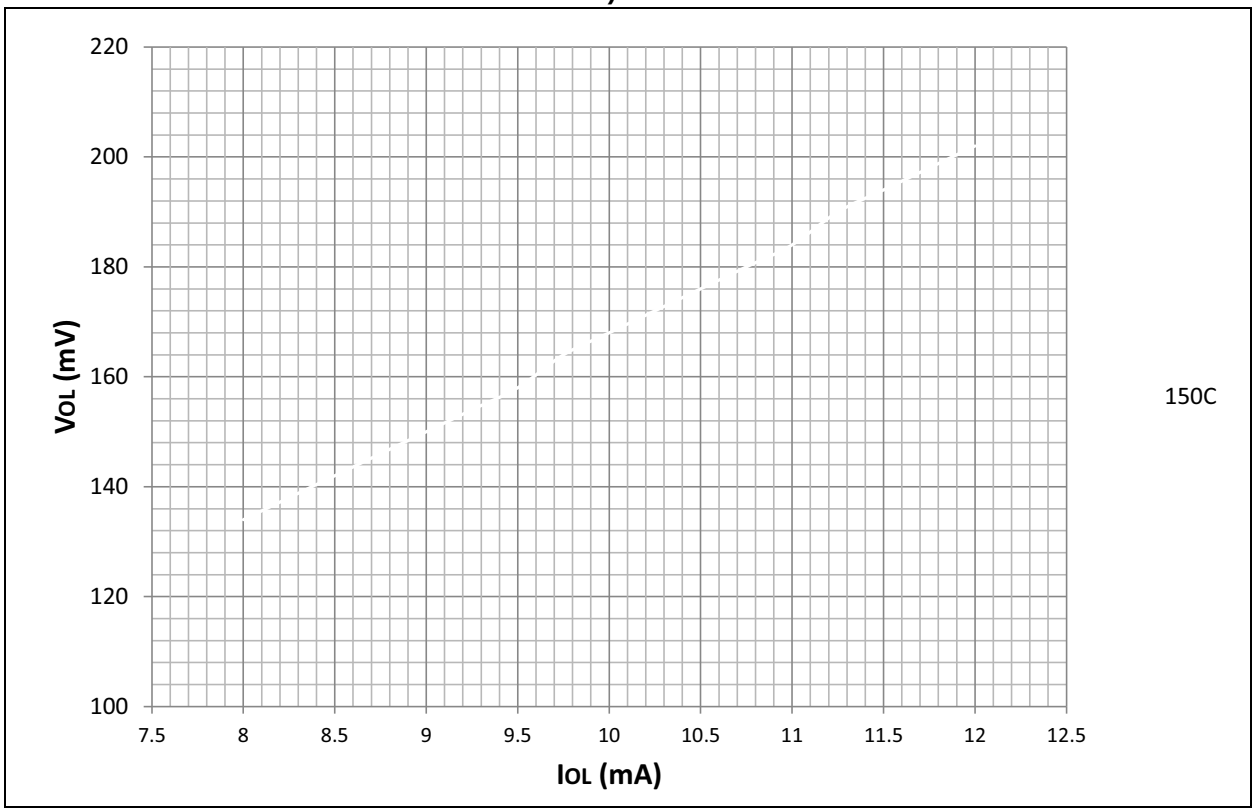
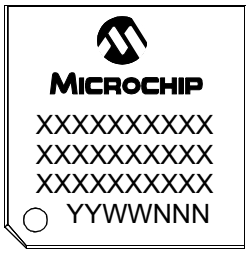


FIGURE 33-28: TYPICAL V_{OL} 8x DRIVER PINS vs. I_{OL} (GENERAL PURPOSE I/Os, TEMPERATURES AS NOTED)



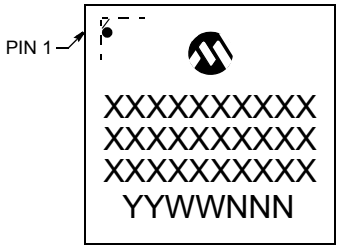
34.1 Package Marking Information (Continued)

44-Lead TQFP (10x10x1 mm)

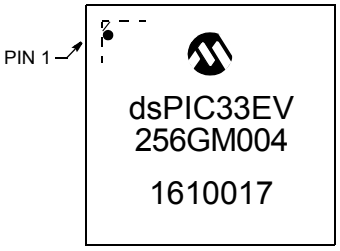


Example

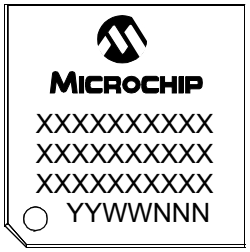
44-Lead QFN (8x8 mm)



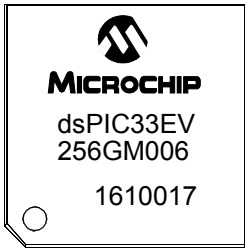
Example



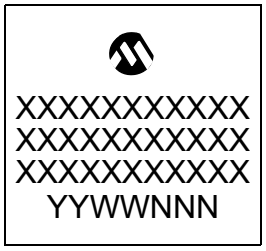
64-Lead TQFP (10x10x1 mm)



Example



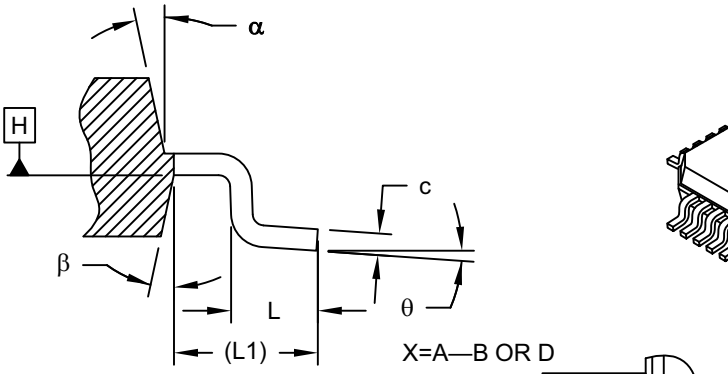
64-Lead QFN (9x9x0.9 mm)



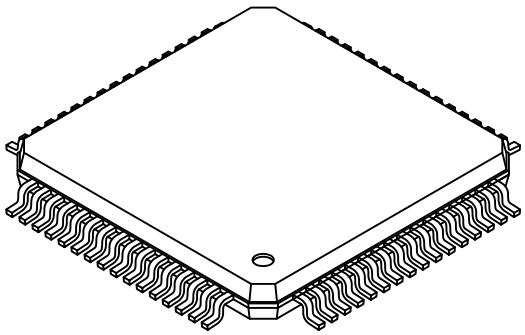
Example

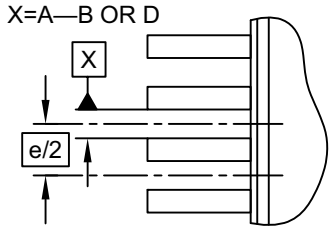
64-Lead Plastic Thin Quad Flatpack (PT)-10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



SECTION A-A





DETAIL 1

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		64	
Lead Pitch	e		0.50 BSC	
Overall Height	A	-	-	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	-	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		12.00 BSC	
Overall Length	D		12.00 BSC	
Molded Package Width	E1		10.00 BSC	
Molded Package Length	D1		10.00 BSC	
Lead Thickness	c	0.09	-	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-085C Sheet 2 of 2